

L Number	Hits	Search Text	DB	Time stamp
1	184659	encapsulat\$ or passivat\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/22 15:09
2	2503	benzocyclobutene or bcb	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/22 15:10
3	5773877	pt or platinum or au or gold or ti or titanium	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/22 15:11
4	422101	cure\$1 or curing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/22 15:12
5	379534	planar\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/22 15:12
6	20	(encapsulat\$ or passivat\$) same (benzocyclobutene or bcb) same (cure\$1 or curing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/22 15:13
7	5	((encapsulat\$ or passivat\$) same (benzocyclobutene or bcb) same (cure\$1 or curing)) and (pt or platinum or au or gold or ti or titanium) and planar\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/22 15:24
9	390590	planar\$ or etch\$3 adj2 back or etchback\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/22 15:27
11	1257280	expos\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/22 15:29
12	1630	(planar\$ or etch\$3 adj2 back or etchback\$) same expos\$5 same (pt or platinum or au or gold or ti or titanium)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/22 15:30
13	9240	(encapsulat\$ or passivat\$) same (cure\$1 or curing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/22 15:30
14	27	((planar\$ or etch\$3 adj2 back or etchback\$) same expos\$5 same (pt or platinum or au or gold or ti or titanium)) and ((encapsulat\$ or passivat\$) same (cure\$1 or curing))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/22 15:47
15	20	(encapsulat\$ or passivat\$) same (benzocyclobutene or bcb) same (cure\$1 or curing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/22 15:49

	Retrieval Classif	Inventor	S	C	P	2	3	4	5
1		Goo, Ju-seon et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
2		Adrian, Ng Choon Seng	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
3		Sachdev, Krishna Gandhi et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
4		Ng, Choon Seng Adrian	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
5		Teong, Jennifer Su Ping	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
6		Carey, David H.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
7		YASUDA, HIDEFUMI et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
8		Yoshimura, Tetsuzo et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
9		Anagnostopoulos, Constantine N. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
10		Bai, Jinchuan	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
11		Yoshimura, Tetsuzo et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
12		Yoshimura, Tetsuzo et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>

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13	<input type="checkbox"/>	<input type="checkbox"/>	US 20020017702 A1	20020214	29
14	<input type="checkbox"/>	<input type="checkbox"/>	US 20020009860 A1	20020124	30
15	<input type="checkbox"/>	<input type="checkbox"/>	US 20010005044 A1	20010628	16
16	<input type="checkbox"/>	<input type="checkbox"/>	US 6343171 B1	20020129	94
17	<input type="checkbox"/>	<input type="checkbox"/>	US 6294830 B1	20010925	16
18	<input type="checkbox"/>	<input type="checkbox"/>	US 6093584 A	20000725	17
19	<input type="checkbox"/>	<input type="checkbox"/>	US 6001671 A	19991214	18
20	<input type="checkbox"/>	<input type="checkbox"/>	US 5874358 A	19990223	11
21	<input type="checkbox"/>	<input type="checkbox"/>	US 5619071 A	19970408	11
22	<input type="checkbox"/>	<input type="checkbox"/>	US 5474958 A	19951212	17

	Title	Current OR	Current XRef
13	Methods for manufacturing resistors using a sacrificial layer	257/536	
14	Methods for manufacturing resistors using a sacrificial layer	438/384	
15	Microelectronic assemblies having exposed conductive terminals and methods therefor	257/678	
16	Systems based on opto-electronic substrates with electrical and optical interconnections and methods for making	385/50	385/14; 385/18; 385/24
17	Microelectronic assembly with conductive terminals having an exposed surface through a dielectric layer	257/724	257/684; 257/730; 257/784; 257/786; 257/787
18	Method for encapsulating a semiconductor package having apertures through a sacrificial layer and contact pads	438/127	438/108; 438/110; 438/119; 438/124; 438/126
19	Methods for manufacturing a semiconductor package having a sacrificial layer	438/112	438/110; 438/126; 438/127
20	Via hole profile and method of fabrication	438/640	438/673; 438/701; 438/754
21	Anchored via connection	257/753	257/763; 257/764; 257/765; 257/774; 257/775; 257/915
22	Method for making semiconductor device having no die supporting surface	29/827	257/676; 257/778; 257/787; 29/841; 29/856; 438/118; 438/124; 438/126

	Retrieval Classif	Inventor	S	C	P	2	3	4	5
13		Fjelstad, Joseph	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
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15		Fjelstad, Joseph	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
16		Yoshimura, Tetsuzo et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
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19		Fjelstad, Joseph	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
20		Myers, Alan M. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
21		Myers, Alan M. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
22		Djennas, Frank et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>

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24	<input type="checkbox"/>	<input type="checkbox"/>	US 5091339 A	19920225	34
25	<input type="checkbox"/>	<input type="checkbox"/>	US 3996066 A	19761207	14
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27	<input type="checkbox"/>	<input type="checkbox"/>	NA82123336	19821201	1

	Title	Current OR	Current XRef
23	Via hole profile and method of fabrication	438/625	257/774; 438/640; 438/666; 438/672; 438/673; 438/688; 438/701
24	Trenching techniques for forming vias and channels in multilayer electrical interconnects	216/18	216/48; 430/312; 438/623; 438/631; 438/940; 438/945
25	Lithium-iodine battery	429/185	29/623.2; 429/213; 607/9
26	Corrosion and Electromigration-Resistant High-Conductivity VLSI Interconnects		
27	Selective Activation of Metal Salt Loaded Polyimide by Exposure to Plasma. December 1982.		

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23		Myers, Alan M. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
24		Carey, David H.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
25		Mead, Ralph T. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
26			<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
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27	NA82123336	<input type="checkbox"/>

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3	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 6121689 A	20000919	22
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7	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 6383916 B	20020507	17
8	<input type="checkbox"/>	<input type="checkbox"/>	US 20020118254 A1	20020829	11
9	<input type="checkbox"/>	<input type="checkbox"/>	US 20020079458 A1	20020627	35
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11	<input type="checkbox"/>	<input type="checkbox"/>	US 20020014703 A1	20020207	18
12	<input type="checkbox"/>	<input type="checkbox"/>	US 20010012642 A1	20010809	11

	Title	Current OR	Current XRef
1	Alignment techniques for epitaxial growth processes	117/90	117/94; 117/95; 117/954; 117/955; 117/96
2	Two layer hermetic-like coating for on-wafer encapsulation of GaAs MMIC's having flip-chip bonding capabilities	257/275	257/640; 257/778
3	Semiconductor flip-chip package and method for the fabrication thereof	257/783	257/773; 257/778; 257/787
4	Multi-layered superconductive interconnects	216/33	216/101; 216/88; 505/410; 505/820
5	Avalanche photodiode with moisture resistant passivation coating disposed to cover the outer periphery of the photodiode body except at a selected top contact area	250/214.1	250/208.1; 257/186
6	MANUFACTURE OF SEMICONDUCTOR DEVICE		
7	Metallic laminate formation, for integrated circuit, involves forming multilayered metallic laminate having metal lines of width greater than metal lines of metallization structure on polyamide layer		
8	Interconnected printhead die and carrier substrate system	347/50	347/40; 347/44
9	Hybrid detector for X-ray imaging	250/370.11	
10	Method for fabricating a semiconductor device	257/200	
11	Semiconductor flip-chip package and method for the fabrication thereof	257/778	438/107
12	Flip-chip package with optimized encapsulant adhesion and method	438/107	438/109

	Retrieval Classif	Inventor	S	C	P	2	3	4	5
1		Hamm, Robert Alan et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
2		Costas, Varmazis D. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
3		Capote, Miguel A. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
4		Chan, Hugo W. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
5		Ishaque, A. Nadeem et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
6		YAMAHATA, SHIYOUJI	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
7		LIN, M	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
8		Wong, Marvin G. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
9		Zur, Albert	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
10		Hwang, Chan Seung	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
11		Capote, Miguel A. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
12		Kodnani, Ramesh R. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>

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12	US 20010012642	<input type="checkbox"/>

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13	<input type="checkbox"/>	<input type="checkbox"/>	US 6466279 B1	20021015	11
14	<input type="checkbox"/>	<input type="checkbox"/>	US 6455408 B1	20020924	15
15	<input type="checkbox"/>	<input type="checkbox"/>	US 6297560 B1	20011002	17
16	<input type="checkbox"/>	<input type="checkbox"/>	US 6249039 B1	20010619	17
17	<input type="checkbox"/>	<input type="checkbox"/>	US 6248614 B1	20010619	10
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20	US 5232970	<input type="checkbox"/>

	Title	Current OR	Current XRef
13	Liquid crystal display device and process for producing same in which forming first and second organic insulating layers using curing and half curing process	349/42	349/122; 349/138; 349/158
14	Method for manufacturing semiconductor devices having redistribution patterns with a concave pattern in a bump pad area	438/613	438/612
15	Semiconductor flip-chip assembly with pre-applied encapsulating layers	257/778	257/701; 257/773; 257/777; 257/779; 257/780; 257/782; 257/783; 257/785; 257/786; 257/789; 257/795
16	Integrated inductive components and method of fabricating such components	257/531	257/528; 257/549; 438/329; 438/381
17	Flip-chip package with optimized encapsulant adhesion and method	438/107	438/108; 438/127; 520/1; 528/44
18	Ink jet printhead which prevents accumulation of air bubbles therein and method of fabrication thereof	347/65	
19	Method for manufacturing an optoelectrical component and an optoelectrical component manufactured according to the method	385/129	385/130; 385/131
20	Ceramic-filled thermally-conductive-composites containing fusible semi-crystalline polyamide and/or polybenzocyclobutenes for use in microelectronic applications	524/404	523/443; 523/445; 523/451; 523/468; 524/414; 524/433; 524/443

	Retrieval Classif	Inventor	S	C	P	2	3	4	5
13		Nakata, Shinichi	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
14		Hwang, Chan Seung et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
15		Capote, Miguel A. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
16		Harvey, Ian Robert et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
17		Kodnani, Ramesh R. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
18		Ims, Dale R. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
19		Palmskog, Goran et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
20		Solc, Jitka et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>